

Abstract

A packaged component according to one of the embodiments of the present invention includes a function chip having a chip surface, a volume-changing material layer formed over the function chip, and a sealing member for sealing the function chip and the volume-changing material layer. At least a part of the chip surface of the function chip is spaced from the volume-changing material layer. Further, the function chip has a peripheral edge portion, and the sealing member supports the function chip at the peripheral edge portion thereof.